

## 40.0A 100V Schottky Barrier Rectifiers

TO-220AB

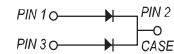
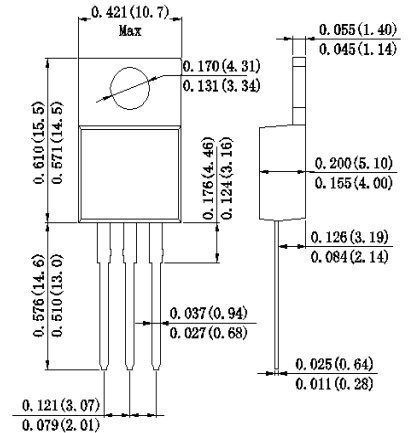


### Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Construction utilizes void-free molded plastic technique
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed 260°C/10 seconds at terminals

### Mechanical Data

- 0.421 (10.7) Max
- 0.170 (4.31) 0.131 (3.34)
- 0.610 (15.5) 0.571 (14.5)
- 0.176 (4.46) 0.124 (3.16)
- 0.576 (14.6) 0.510 (13.0)
- 0.037 (0.94) 0.027 (0.68)
- 0.121 (3.07) 0.079 (2.01)
- 0.055 (1.40) 0.045 (1.14)
- 0.200 (5.10) 0.155 (4.00)
- 0.126 (3.19) 0.084 (2.14)
- 0.025 (0.64) 0.011 (0.28)



Dimensions in inches and (millimeters)

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbols	MBR40100CT	Units
Maximum repetitive peak reverse voltage	$V_{RRM}$	100	V
Maximum RMS voltage	$V_{RMS}$	70	V
Maximum DC blocking voltage	$V_{DC}$	100	V
Maximum average forward rectified current at $T_c=110^\circ\text{C}$	$I_{(AV)}$	Per device 40.0	A
		Per diode 20.0	
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	250.0	A
Typical thermal resistance	$R_{qJC}$	2.0	$^\circ\text{C/W}$
Operating junction temperature range	$T_J$	-55 to +150	$^\circ\text{C}$
Storage temperature range	$T_{STG}$	-55 to +150	$^\circ\text{C}$

Parameter	Symbols	Type	Max	Units
Maximum instantaneous forward voltage per diode at 20.0A	$V_F$	0.84	0.88	V
Maximum DC reverse current at rated DC blocking voltage	$I_R$	$T_A=25^\circ\text{C}$	5	$\mu\text{A}$
		$T_A=100^\circ\text{C}$	20	$\text{mA}$



Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

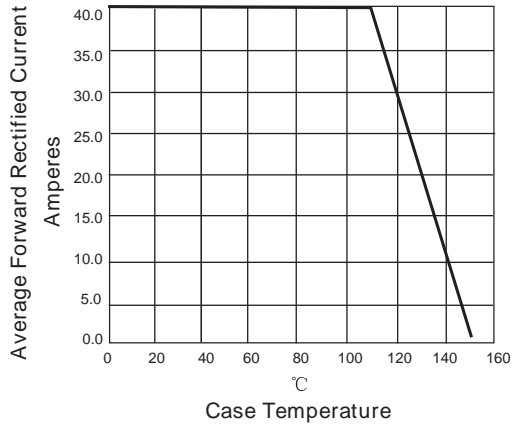


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

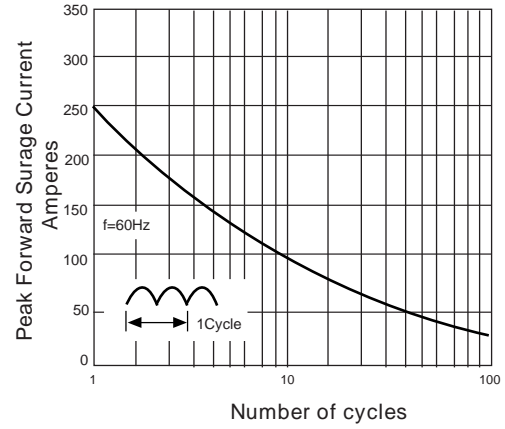


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

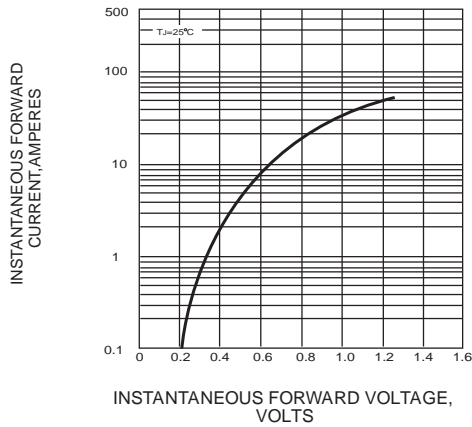
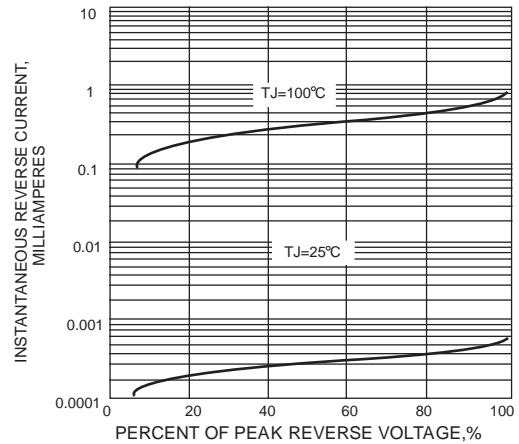
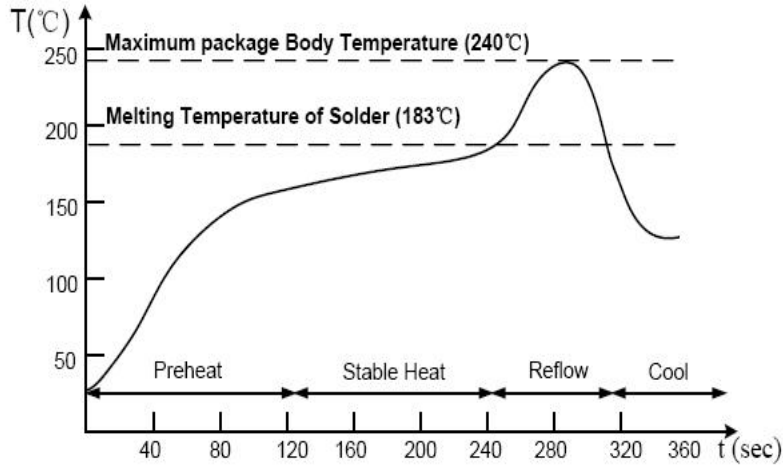


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



## Suggested Soldering Temperature Profile



### Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

## Package Information

### Tube Package

Package	Tube (mm)	Q'TY/Tube (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
TO-220AB	525*31.9*6.4	0.05	545*150*45	1.0	575*245*170	5.0